

HEADERS & RECEPTACLES





PRODUCT DRAWING



3D PDF

TE CONNECTIVITY (TE)

05 MTE HDR SRRA LATCH W/HLDWN

AMPMODU | AMPMODU MTE

103673-4

TE Internal Number: 103673-4

Not EU RoHS or ELV Compliant Find Compliant Alternatives

Centerline 2.54 mm [.1 in]

Number of Positions 5

PCB Mounting Orientation Right Angle

PCB Mounting Style Through Hole

Number of Rows 1

Product Drawings

HDR ASSY, RTANG, SINGLE ROW 2.54[.100] C/L 0.641[.025] SQ. POST, WITH

PLZN & HOLD DOWNS, AMPMODU MTE

PDF English

CAD Files

Customer View Model

2D_DXF.ZIP English

Customer View Model

3D_IGS.ZIP English

Customer View Model

3D_STP.ZIP English

3D PDF

PDF **English**

Catalog Pages/Data Sheets

AMPMODU_MTE_INTERCONNECT_SYSTEM_QRG_4-1773458-0

PDF **English**

Product Specifications

Application Specification AMPMODU MTE Interconnection System

PDF **English**

Product Environmental Compliance

TE Material Declaration MD_103673-4_080420151049_dmtec

PDF **English**

Instruction Sheets

Instruction Sheet (U.S.) **AMPMODU MTE CONNECTORS**

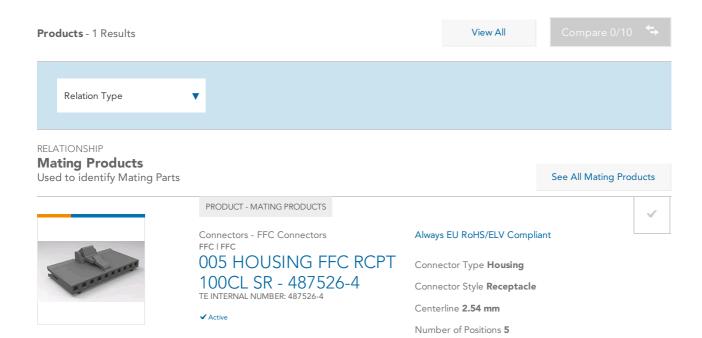
English

Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.

Product Type Features	PCB Mounting Orientation	Right Angle
	Product Type	Connector
	Connector Type	Header
	Strain Relief	Without
	Row-to-Row Spacing	2.54 mm [.1 in]
	Connector Style	Plug
	PCB Orientation Feature	No
	Applies To	Printed Circuit Board
Configuration Features	Number of Positions	5
	Number of Rows	1
	Backwall/Post Interruptions	Without
Electrical Characteristics	Dielectric Withstanding Voltage	600 V
	Insulation Resistance	5000 ΜΩ
	Termination Resistance	15 ΜΩ
Body Features	Header Type	Shrouded
Body Features Contact Features	Header Type Contact Mating Area Plating Material	Shrouded
	Contact Mating Area Plating Material	Gold
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin)	Gold 15
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness	Gold 15 2.54 μm [100 μin]
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape	Gold 15 2.54 μm [100 μin] Square
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material	Gold 15 2.54 μm [100 μin] Square Tin-Lead
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material Tail Plating Material	Gold 15 2.54 μm [100 μin] Square Tin-Lead Tin-Lead
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material Tail Plating Material Tail Plating Thickness	Gold 15 2.54 μm [100 μin] Square Tin-Lead Tin-Lead 2.54 μm [100 μin]
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material Tail Plating Material Tail Plating Thickness Contact Type	Gold 15 2.54 μm [100 μin] Square Tin-Lead Tin-Lead 2.54 μm [100 μin]
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material Tail Plating Material Tail Plating Thickness Contact Type Solder Tail Contact Plating Material	Gold 15 2.54 µm [100 µin] Square Tin-Lead Tin-Lead 2.54 µm [100 µin] Pin Tin-Lead
	Contact Mating Area Plating Material Contact Mating Area Plating Thickness (µin) Contact Termination Area Plating Thickness Contact Shape Contact Termination Area Plating Material Tail Plating Material Tail Plating Thickness Contact Type Solder Tail Contact Plating Material Contact Current Rating (A) Contact Termination Area Plating Material	Gold 15 2.54 μm [100 μin] Square Tin-Lead Tin-Lead 2.54 μm [100 μin] Pin Tin-Lead

Termination Features	Termination Method to Wire/Cable	Crimp, Insulation Displacement Crimp (IDC)
Mechanical Attachment	PCB Mounting Style	Through Hole
	PCB Mount Alignment	Without
	Mating Retention	With
	PCB Mount Retention	With
	PCB Mount Retention Type	Hold-Down
	Contact Retention	With
	Mating Alignment Type	Latched
	Contact Retention Type	Locking Lance
	Mating Retention Type	Hold-Down
	Mating Alignment	With
Housing Features	Centerline	2.54 mm [.1 in]
	Housing Color	Black
	Housing Material	Thermoplastic
Dimensions	Tail Length	3.3 mm [.13 in]
	Mating Post Length	5.84 mm [.23 in]
	PCB Thickness (Recommended)	1.57 mm [.062 in]
	Height	13.59 mm [.535 in]
	Length	15.24 mm [.6 in]
Usage Conditions	Operating Temperature Range (°C)	-65 – 105
Operation/Application	For Use With	Receptacle Housing Assembly
	Pick and Place Cover	Without
Industry Standards	UL Flammability Rating	UL 94V-0
	Approved Standards	CSA LR7189, UL E28476
Packaging Features	Packaging Method	Tube, Tube/Box
	Packaging Quantity	35
Other	Comment	Use Keying Tool No. 91417-1 to remove post for keying.

VIEW ALL PRODUCT COMPLIANCE



Number of Rows 1